

# STS25NH3LL

# N-CHANNEL 30V - 0.0032 $\Omega$ - 25A SO-8 STripFETTM III MOSFET FOR DC-DC CONVERSION

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	ΙD	
STS25NH3LL	30 V	<0.0035 Ω	25 A	

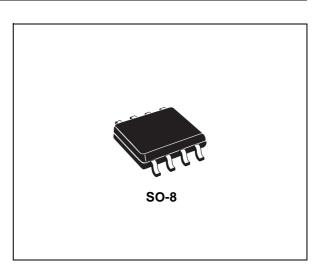
- TYPICAL  $R_{DS}(on) = 0.0032 \Omega @ 10V$
- OPTIMAL R<sub>DS</sub>(on) x Qg TRADE-OFF @ 4.5V
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

#### **DESCRIPTION**

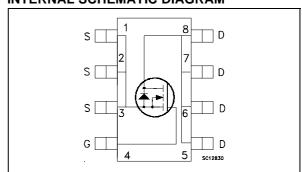
The STS25NH3LL utilizes the latest advanced design rules of ST's propetary STripFETTM technology. This novel  $0.6\mu$  process coupled to unique metalization techniques re alizes the most advanced low voltage MOSFET in SO-8 ever produced. It is therefore suit able for the most demanding DC-DC converter applications where high efficiency is to be achived at high output current.

#### **APPLICATIONS**

- DC-DC CONVERTERS FOR TELECOM AND NOTEBOOK CPU CORE
- SYNCHRONOUS RECTIFIER



#### **INTERNAL SCHEMATIC DIAGRAM**



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	bol Parameter Value		Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
$V_{DGR}$	Drain-gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	30	V
$V_{GS}$	Gate- source Voltage	± 18	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	25	Α
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 100°C	18	Α
I <sub>DM</sub> (•)	Drain Current (pulsed)	100	Α
E <sub>AS</sub> (1)	Single Pulse Avalanche Energy	200	mJ
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25°C	3.2	W

<sup>(•)</sup> Pulse width limited by safe operating area.

(1) Starting  $T_j = 25 \text{ °C}$   $I_D = 12.5 \text{A}$   $V_{DD} = 30 \text{V}$ 

April 2003 1/8

.

# THERMAL DATA

Rthj-amb Rthj-lead T <sub>j</sub> T <sub>stq</sub>	(*)Thermal Resistance Junction-ambient Max Thermal Resistance Junction-leads Max Maximum Operating Junction Temperature Storage Temperature	47 16 -55 to 175 -55 to 175	°C/W °C/W °C/W	
rstg	Storage Temperature	-55 to 175		

<sup>(\*)</sup> When Mounted on 1 inch² FR-4 board, 2 oz of Cu and t  $\leq$  10 sec.

# **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

# OFF

Symbol	Parameter	Test Conditions Mi		Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating T_C = 125^{\circ}C$			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 18 V			±100	nA

# ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250 μA	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 12.5 A I <sub>D</sub> = 12.5 A		0.0032 0.004	0.0035 0.005	Ω Ω

# **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	$V_{DS} = 10 \text{ V}$ $I_D = 12.5 \text{ A}$		30		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$ , $f = 1 MHz$ , $V_{GS} = 0$		4450 655 50		pF pF pF

# **ELECTRICAL CHARACTERISTICS** (continued)

# **SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time	$\begin{aligned} V_{DD} &= 15 \text{ V} & I_D &= 12.5 \text{ A} \\ R_G &= 4.7 \ \Omega & V_{GS} &= 10 \text{ V} \\ \text{(Resistive Load, Figure 1)} \end{aligned}$		18 50		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD}$ =15V $I_{D}$ =25A $V_{GS}$ =4.5 V (see test circuit, Figure 2)		30 12.5 10	40	nC nC nC

# **SWITCHING OFF**

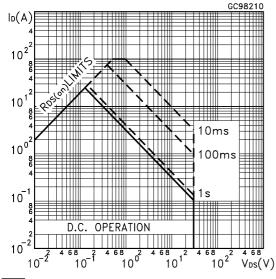
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time	$V_{DD}$ = 15 V $R_G$ = 4.7 $\Omega$ , (Resistive Loa	$I_D = 12.5 \text{ A}$ $V_{GS} = 10 \text{ V}$ d, Figure 3)		75 8		ns ns

# SOURCE DRAIN DIODE

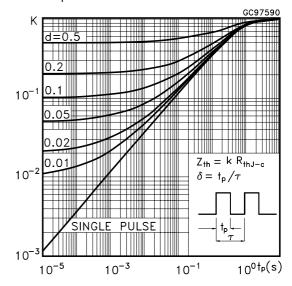
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				25 100	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 25 A V <sub>GS</sub> = 0			1.2	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$\begin{split} I_{SD} = 25 \text{ A} & \text{di/dt} = 100 \text{A/}\mu\text{s} \\ V_{DD} = 25 \text{ V} & T_j = 150 ^{\circ}\text{C} \\ \text{(see test circuit, Figure 3)} \end{split}$		32 34 2.1		ns nC A

<sup>(\*)</sup>Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

# Safe Operating Area

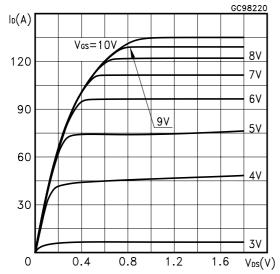


#### Thermal Impedance

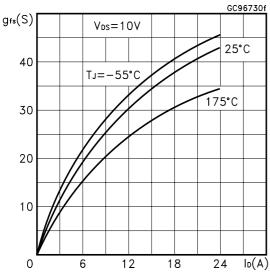


4

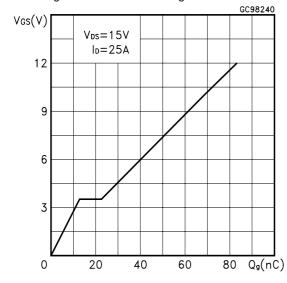
# **Output Characteristics**



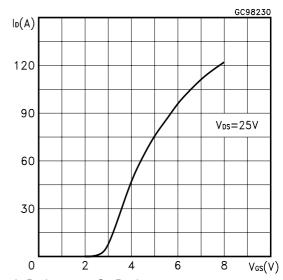
#### Transconductance



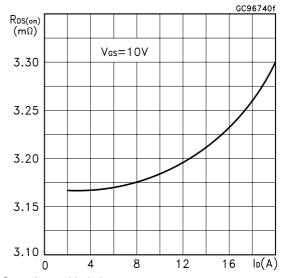
Gate Charge vs Gate-source Voltage



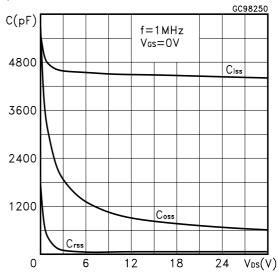
# Transfer Characteristics



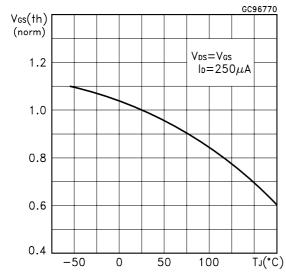
Static Drain-source On Resistance



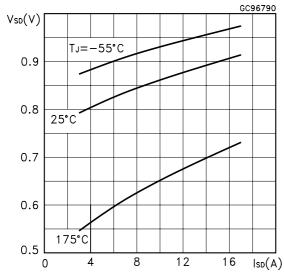
# Capacitance Variations



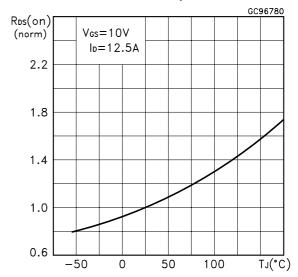
# Normalized Gate Threshold Voltage vs Temperature



# Source-drain Diode Forward Characteristics



# Normalized on Resistance vs Temperature



# Normalized Breakdown Voltage vs Temperature.

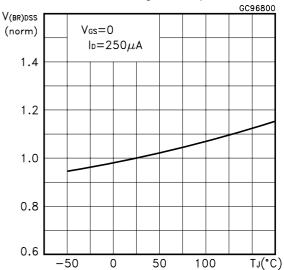


Fig. 1: Switching Times Test Circuits For Resistive Load

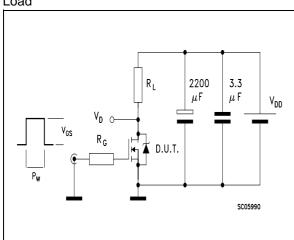


Fig. 2: Gate Charge test Circuit

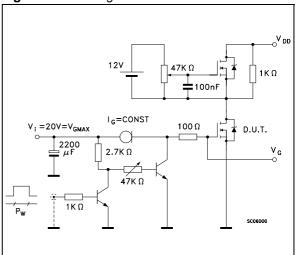
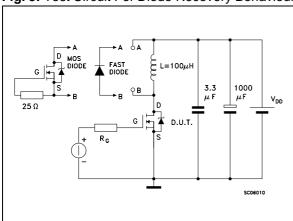
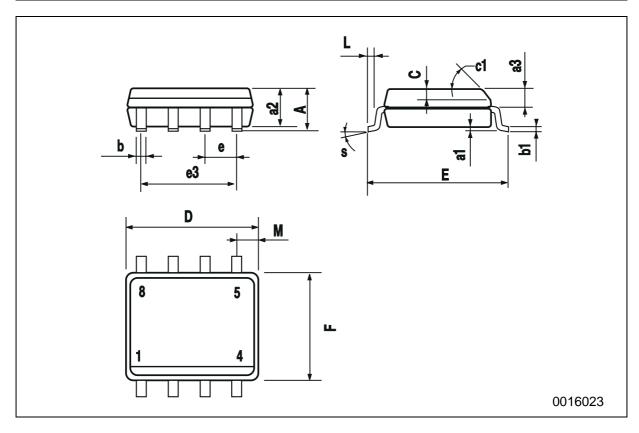


Fig. 3: Test Circuit For Diode Recovery Behaviour



# **SO-8 MECHANICAL DATA**

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)		



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is registered trademark of STMicroelectronics ® 2003 STMicroelectronics - All Rights Reserved

All other names are the property of their respective owners.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States.

http://www.st.com